

November 1994

LMC6064

Precision CMOS Quad Micropower Operational Amplifier

General Description

The LMC6064 is a precision quad low offset voltage, micropower operational amplifier, capable of precision single supply operation. Performance characteristics include ultra low input bias current, high voltage gain, rail-to-rail output swing, and an input common mode voltage range that includes ground. These features, plus its low power consumption make the LMC6064 ideally suited for battery powered applications.

Other applications using the LMC6064 include precision full-wave rectifiers, integrators, references, sample-and-hold circuits, and true instrumentation amplifiers.

This device is built with National's advanced double-Poly Silicon-Gate CMOS process.

For designs that require higher speed, see the LMC6084 precision quad operational amplifier.

For single or dual operational amplifier with similar features, see the LMC6061 or LMC6062 respectively.

PATENT PENDING

Features

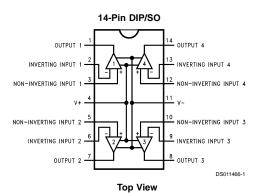
(Typical Unless Otherwise Noted)

- Low offset voltage: 100 µV
- Ultra low supply current: 16 µA/Amplifier
- Operates from 4.5V to 15V single supply
- Ultra low input bias current: 10 fA
- Output swing within 10 mV of supply rail, 100k load
- Input common-mode range includes V⁻
- High voltage gain: 140 dB
- Improved latchup immunity

Applications

- Instrumentation amplifier
- Photodiode and infrared detector preamplifier
- Transducer amplifiers
- Hand-held analytic instruments
- Medical instrumentation
- D/A converter
- Charge amplifier for piezoelectric transducers

Connection Diagram



Ordering Information

	Tempera	ture Range	NOO	-	
Package	Military Industrial		NSC	Transport Media	
	-55°C to +125°C	-40°C to +85°C	Drawing	wedia	
14-Pin	LMC6064AMN	LMC6064AIN	N14A	Rail	
Molded DIP		LMC6064IN			
14-Pin		LMC6064AIM	M14A	Rail	
Small Outline		LMC6064IM		Tape and Reel	
14-Pin	LMC6064AMJ		J14A	Rail	
Ceramic DIP					

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

(Soldering, 10 sec.) 260°C

Storage Temp. Range -65°C to +150°C

Junction Temperature 150°C

ESD Tolerance (Note 4) 2 kV

Current at Input Pin ±10 mA
Current at Output Pin ±30 mA
Current at Power Supply Pin 40 mA
Power Dissipation (Note 3)

Operating Ratings (Note 1)

Temperature Range

LMC6064AM -55° C ≤ T_J ≤ +125 $^{\circ}$ C LMC6064AI, LMC6064I -40° C ≤ T_J ≤ +85 $^{\circ}$ C Supply Voltage 4.5V ≤ V⁺ ≤ 15.5V

Thermal Resistance (θ_{JA}) (Note 12)

 14-Pin Molded DIP
 81°C/W

 14-Pin SO
 126°C/W

 Power Dissipation
 (Note 10)

DC Electrical Characteristics

Unless otherwise specified, all limits guaranteed for T_J = 25°C. **Boldface** limits apply at the temperature extremes. V^+ = 5V, V^- = 0V, V_{CM} = 1.5V, V_O = 2.5V and R_L > 1M unless otherwise specified.

				Тур	LMC6064AM	LMC6064AI	LMC6064I	
Symbol	Parameter	Condit	ions	(Note 5)	Limit	Limit	Limit	Units
					(Note 6)	(Note 6)	(Note 6)	
Vos	Input Offset Voltage			100	350	350	800	μV
					1200	900	1300	Max
TCVos	Input Offset Voltage			1.0				μV/°C
	Average Drift							
I _B	Input Bias Current			0.010				pА
					100	4	4	Max
los	Input Offset Current			0.005				pА
					100	2	2	Max
R _{IN}	Input Resistance			>10				Tera Ω
CMRR	Common Mode	0V ≤ V _{CM} ≤ 12	2.0V	85	75	75	66	dB
	Rejection Ratio	V+ = 15V			70	72	63	Min
+PSRR	Positive Power Supply	5V ≤ V ⁺ ≤ 15V	1	85	75	75	66	dB
	Rejection Ratio	V _O = 2.5V			70	72	63	Min
-PSRR	Negative Power Supply	0V ≤ V ⁻ ≤ −10V		100	84	84	74	dB
	Rejection Ratio				70	81	71	Min
V _{CM}	Input Common-Mode	V ⁺ = 5V and 1	5V	-0.4	-0.1	-0.1	-0.1	V
	Voltage Range	for CMRR ≥ 60 dB			0	0	0	Max
				V+ - 1.9	V+ - 2.3	V+ - 2.3	V+ - 2.3	V
					V+ - 2.6	V+ - 2.5	V+ - 2.5	Min
A _V	Large Signal	$R_L = 100 \text{ k}\Omega$	Sourcing	4000	400	400	300	V/mV
	Voltage Gain	(Note 7)			200	300	200	Min
			Sinking	3000	180	180	90	V/mV
					70	100	60	Min
		$R_L = 25 \text{ k}\Omega$	Sourcing	3000	400	400	200	V/mV
		(Note 7)			150	150	80	Min
			Sinking	2000	100	100	70	V/mV
					35	50	35	Min

DC Electrical Characteristics (Continued)

Unless otherwise specified, all limits guaranteed for T_J = 25°C. **Boldface** limits apply at the temperature extremes. V⁺ = 5V, V⁻ = 0V, V_{CM} = 1.5V, V_O = 2.5V and R_L > 1M unless otherwise specified.

			Тур	LMC6064AM	LMC6064AI	LMC6064I	
Symbol	Parameter	Conditions	(Note 5)	Limit	Limit	Limit	Units
				(Note 6)	(Note 6)	(Note 6)	
Vo	Output Swing	V+ = 5V	4.995	4.990	4.990	4.950	V
		$R_{L} = 100 \text{ k}\Omega \text{ to } 2.5 \text{V}$		4.970	4.980	4.925	Min
			0.005	0.010	0.010	0.050	V
				0.030	0.020	0.075	Max
		V+ = 5V	4.990	4.975	4.975	4.950	V
		$R_L = 25 \text{ k}\Omega \text{ to } 2.5\text{V}$		4.955	4.965	4.850	Min
			0.010	0.020	0.020	0.050	V
				0.045	0.035	0.150	Max
		V+ = 15V	14.990	14.975	14.975	14.950	V
		$R_{L} = 100 \text{ k}\Omega \text{ to } 7.5 \text{V}$		14.955	14.965	14.925	Min
			0.010	0.025	0.025	0.050	V
				0.050	0.035	0.075	Max
		V+ = 15V	14.965	14.900	14.900	14.850	V
		$R_L = 25 \text{ k}\Omega \text{ to } 7.5 \text{V}$		14.800	14.850	14.800	Min
			0.025	0.050	0.050	0.100	V
				0.200	0.150	0.200	Max
I _O	Output Current	Sourcing, V _O = 0V	22	16	16	13	mA
	V ⁺ = 5V			8	10	8	Min
		Sinking, V _O = 5V	21	16	16	16	mA
				7	8	8	Min
I _O	Output Current	Sourcing, V _O = 0V	25	15	15	15	mA
	V ⁺ = 15V			9	10	10	Min
		Sinking, V _O = 13V	35	24	24	24	mA
		(Note 11)		7	8	8	Min
I _s	Supply Current	All Four Amplifiers	64	76	76	92	μA
		$V^{+} = +5V, V_{O} = 1.5V$		120	92	112	Max
		All Four Amplifiers		94	94	114	μA
		$V^+ = +15V, V_O = 7.5V$	80	140	110	132	Max

AC Electrical Characteristics

Unless otherwise specified, all limits guaranteed for T_J = 25°C, **Boldface** limits apply at the temperature extremes. V^+ = 5V, V^- = 0V, V_{CM} = 1.5V, V_O = 2.5V and R_L > 1M unless otherwise specified.

			Тур	LMC6064AM	LMC6064AI	LMC6064I	
Symbol	Parameter	Conditions	(Note 5)	Limit	Limit	Limit	Units
				(Note 6)	(Note 6)	(Note 6)	
SR	Slew Rate	(Note 8)	35	20	20	15	V/ms
				8	10	7	Min
GBW	Gain-Bandwidth Product		100				kHz
θ_{m}	Phase Margin		50				Deg
	Amp-to-Amp Isolation	(Note 9)	155				dB
en	Input-Referred Voltage Noise	F = 1 kHz	83				nV∕t√ Hz
i _n	Input-Referred Current Noise	F = 1 kHz	0.0002				pA/√ Hz
T.H.D.	Total Harmonic Distortion	F = 1 kHz, A _V = -5					
		$R_L = 100 \text{ k}\Omega, V_O = 2 V_{PP}$	0.01				%
		±5V Supply					

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed.

Note 2: Applies to both single-supply and split-supply operation. Continous short circuit operation at elevated ambient temperature can result in exceeding the maximum allowed junction temperature of 150°C. Output currents in excess of ±30 mA over long term may adversely affect reliability.

Note 3: The maximum power dissipation is a function of $T_{J(Max)}$. θ_{JA} , and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(Max)} - T_A)\theta_{JA}$.

Note 4: Human body model, 1.5 k Ω in series with 100 pF.

Note 5: Typical values represent the most likely parametric norm.

Note 6: All limits are guaranteed by testing or statistical analysis.

Note 7: V^+ = 15V, V_{CM} = 7.5V and R_L connected to 7.5V. For Sourcing tests, 7.5V \leq $V_O \leq$ 11.5V. For Sinking tests, 2.5V \leq $V_O \leq$ 7.5V.

Note 8: V⁺ = 15V. Connected as Voltage Follower with 10V step input. Number specified is the slower of the positive and negative slew rates.

Note 9: Input referred V* = 15V and R_L = 100 k Ω connected to 7.5V. Each amp excited in turn with 100 Hz to produce V_O = 12 V_{PP} .

Note 10: For operating at elevated temperatures the device must be derated based on the thermal resistance θ_{JA} with $P_D = (T_J - T_A)/\theta_{JA}$.

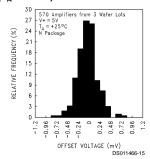
Note 11: Do not connect output to V^+ , when V^+ is greater than 13V or reliability witll be adversely affected. Note 12: All numbers apply for packages soldered directly into a PC board.

Note 13: For guaranteed Military Temperature Range parameters see RETSMC6064X.

Typical Performance Characteristics

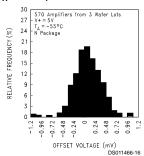
Distribution of LMC6064 Input Offset Voltage

 $(T_A = +25^{\circ}C)$



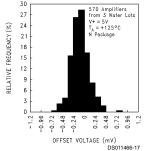
Distribution of LMC6064 Input Offset Voltage

 $(T_A = -55^{\circ}C)$



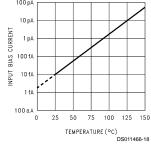
Distribution of LMC6064 Input Offset Voltage (T_A = +125°C)

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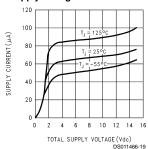


Input Bias Current vs Temperature

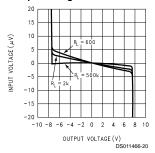




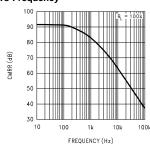
Supply Current vs Supply Voltage



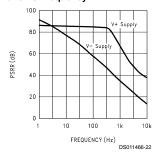
Input Voltage vs Output Voltage



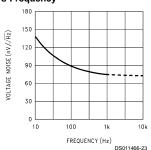
Common Mode Rejection Ratio vs Frequency



Power Supply Rejection Ratio vs Frequency

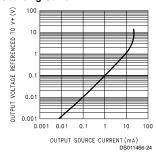


Input Voltage Noise vs Frequency

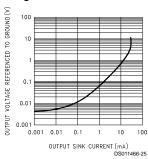


Typical Performance Characteristics (Continued)

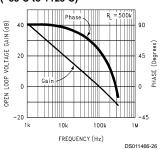
Output Characteristics Sourcing Current



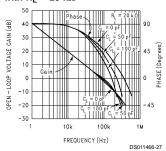
Output Characteristics Sinking Current



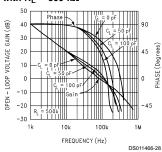
Gain and Phase Response vs Temperature (-55°C to +125°C)



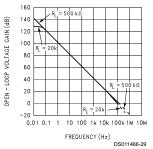
Gain and Phase Response vs Capacitive Load with R $_{\rm L}$ = 20 k Ω



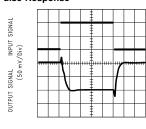
Gain and Phase Response vs Capacitive Load with R $_{L}$ = 500 $k\Omega$



Open Loop Frequency Response

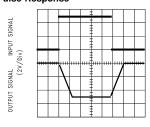


Inverting Small Signal Pulse Response



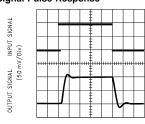
TIME (10 μs/Div)
DS011466-30

Inverting Large Signal Pulse Response



TIME (100 μs/Div)
DS011466-31

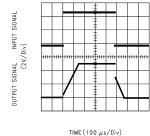
Non-Inverting Small Signal Pulse Response



TIME (10 µs/Div)
DS011466-32

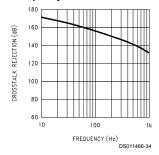
Typical Performance Characteristics (Continued)

Non-Inverting Large Signal Pulse Response

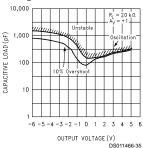


DS011466-33

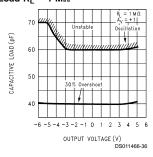
Crosstalk Rejection vs Frequency



Stability vs Capacitive Load, $R_L = 20 \text{ k}\Omega$



Stability vs Capacitive Load R_L = 1 M Ω



Applications Hints

AMPLIFIER TOPOLOGY

The LMC6064 incorporates a novel op-amp design topology that enables it to maintain rail-to-rail output swing even when driving a large load. Instead of relying on a push-pull unity gain output buffer stage, the output stage is taken directly from the internal integrator, which provides both low output impedance and large gain. Special feed-forward compensation design techniques are incorporated to maintain stability over a wider range of operating conditions than traditional micropower op-amps. These features make the LMC6064 both easier to design with, and provide higher speed than products typically found in this ultra-low power class.

COMPENSATING FOR INPUT CAPACITANCE

It is quite common to use large values of feedback resistance for amplifiers with ultra-low input current, like the LMC6064.

Although the LMC6064 is highly stable over a wide range of operating conditions, certain precautions must be met to achieve the desired pulse response when a large feedback resistor is used. Large feedback resistors and even small values of input capacitance, due to transducers, photodiodes, and circuit board parasitics, reduce phase margins. When high input impedances are demanded, guarding of the

LMC6064 is suggested. Guarding input lines will not only reduce leakage, but lowers stray input capacitance as well. (See Printed-Circuit-Board Layout for High Impedance Work).

The effect of input capacitance can be compensated for by adding a capacitor. Place a capacitor, Cf, around the feedback resistor (as in Figure 1) such that:

$$\frac{1}{2\pi R_1 C_{\text{IN}}} \ge \frac{1}{2\pi R_2 C_{\text{f}}}$$

 $R_1 \ C_{IN} \leq R_2 \ C_f$

Since it is often difficult to know the exact value of CIN, Cf can be experimentally adjusted so that the desired pulse response is achieved. Refer to the LMC660 and the LMC662 for a more detailed discussion on compensating for input capacitance.

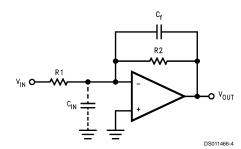


FIGURE 1. Canceling the Effect of Input Capacitance

Applications Hints (Continued)

CAPACITIVE LOAD TOLERANCE

All rail-to-rail output swing operational amplifiers have voltage gain in the output stage. A compensation capacitor is normally included in this integrator stage. The frequency location of the dominate pole is affected by the resistive load on the amplifier. Capacitive load driving capability can be optimized by using an appropriate resistive load in parallel with the capacitive load (see typical curves).

Direct capacitive loading will reduce the phase margin of many op-amps. A pole in the feedback loop is created by the combination of the op-amp's output impedance and the capacitive load. This pole induces phase lag at the unity-gain crossover frequency of the amplifier resulting in either an oscillatory or underdamped pulse response. With a few external components, op amps can easily indirectly drive capacitive loads, as shown in Figure 2.

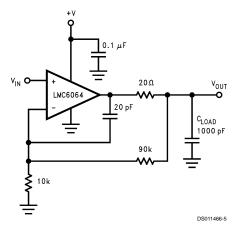


FIGURE 2. LMC6064 Noninverting Gain of 10 Amplifier, Compensated to Handle Capacitive Loads

In the circuit of *Figure 2*, R1 and C1 serve to counteract the loss of phase margin by feeding the high frequency component of the output signal back to the amplifier's inverting input, thereby preserving phase margin in the overall feedback loop.

Capacitive load driving capability is enhanced by using a pull up resistor to V⁺ (*Figure 3*). Typically a pull up resistor conducting 10 μ A or more will significantly improve capacitive load responses. The value of the pull up resistor must be determined based on the current sinking capability of the amplifier with respect to the desired output swing. Open loop gain of the amplifier can also be affected by the pull up resistor (see Electrical Characteristics).

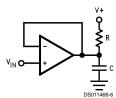


FIGURE 3. Compensating for Large Capacitive Loads with a Pull Up Resistor

PRINTED-CIRCUIT-BOARD LAYOUT FOR HIGH-IMPEDANCE WORK

It is generally recognized that any circuit which must operate with less than 1000 pA of leakage current requires special layout of the PC board. When one wishes to take advantage of the ultra-low bias current of the LMC6064, typically less than 10 fA, it is essential to have an excellent layout. Fortunately, the techniques of obtaining low leakages are quite simple. First, the user must not ignore the surface leakage of the PC board, even though it may sometimes appear acceptably low, because under conditions of high humidity or dust or contamination, the surface leakage will be appreciable.

To minimize the effect of any surface leakage, lay out a ring of foil completely surrounding the LMC6064's inputs and the terminals of capacitors, diodes, conductors, resistors, relay terminals etc. connected to the op-amp's inputs, as in Figure 4. To have a significant effect, guard rings should be placed on both the top and bottom of the PC board. This PC foil must then be connected to a voltage which is at the same voltage as the amplifier inputs, since no leakage current can flow between two points at the same potential. For example, a PC board trace-to-pad resistance of $10^{12}\Omega$, which is normally considered a very large resistance, could leak 5 pA if the trace were a 5V bus adjacent to the pad of the input. This would cause a 100 times degradation from the LMC6064's actual performance. However, if a guard ring is held within 5 mV of the inputs, then even a resistance of $10^{11}\Omega$ would cause only 0.05 pA of leakage current. See Figure 5 for typical connections of guard rings for standard op-amp configurations.

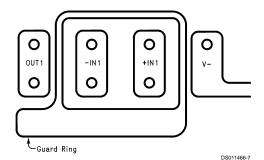
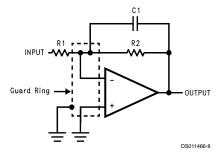
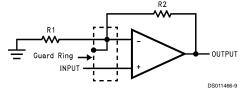


FIGURE 4. Example of Guard Ring in P.C. Board Layout

Applications Hints (Continued)



Inverting Amplifier



Non-Inverting Amplifier

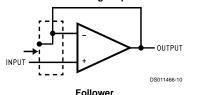
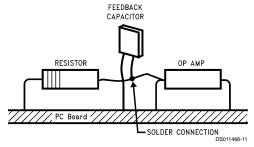


FIGURE 5. Typical Connections of Guard Rings

The designer should be aware that when it is inappropriate to lay out a PC board for the sake of just a few circuits, there is another technique which is even better than a guard ring on a PC board: Don't insert the amplifier's input pin into the board at all, but bend it up in the air and use only air as an insulator. Air is an excellent insulator. In this case you may have to forego some of the advantages of PC board construction, but the advantages are sometimes well worth the effort of using point-to-point up-in-the-air wiring. See *Figure* 6

Latchup

CMOS devices tend to be susceptible to latchup due to their internal parasitic SCR effects. The (I/O) input and output pins look similar to the gate of the SCR. There is a minimum current required to trigger the SCR gate lead. The LMC6064 and LMC6082 are designed to withstand 100 mA surge current on the I/O pins. Some resistive method should be used to isolate any capacitance from supplying excess current to the I/O pins. In addition, like an SCR, there is a minimum holding current for any latchup mode. Limiting current to the supply pins will also inhibit latchup susceptibility.



(Input pins are lifted out of PC board and soldered directly to components. All other pins connected to PC board).

FIGURE 6. Air Wiring

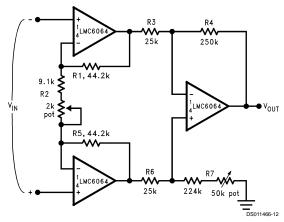
Typical Single-Supply Applications

 $(V^{+} = 5.0 V_{DC})$

The extremely high input impedance, and low power consumption, of the LMC6064 make it ideal for applications that require battery-powered instrumentation amplifiers. Examples of these types of applications are hand-held pH probes, analytic medical instruments, magnetic field detectors, gas detectors, and silicon based pressure transducers.

Figure 7 shows an instrumentation amplifier that features high differential and common mode input resistance (>101 $^4\Omega$), 0.01% gain accuracy at $A_V=100$, excellent CMRR with 1 kΩ imbalance in bridge source resistance. Input current is less than 100 fA and offset drift is less than 2.5 μV/°C. R_2 provides a simple means of adjusting gain over a wide range without degrading CMRR. R_7 is an initial trim used to maximize CMRR without using super precision matched resistors. For good CMRR over temperature, low drift resistors should be used.

Typical Single-Supply Applications (Continued)



If $R_1 = R_5$, $R_3 = R_6$, and $R_4 = R_7$; then

$$\frac{v_{OUT}}{v_{IN}} = \frac{R_2 + 2R_1}{R_2} \times \frac{R_4}{R_3}$$

 $\therefore A_V \approx 100$ for circuit shown (R₂ = 9.822k).

FIGURE 7. Instrumentation Amplifier

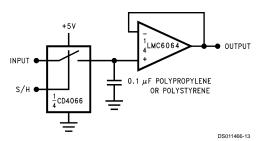


FIGURE 8. Low-Leakage Sample and Hold

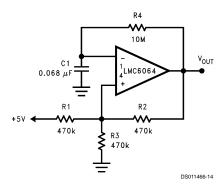
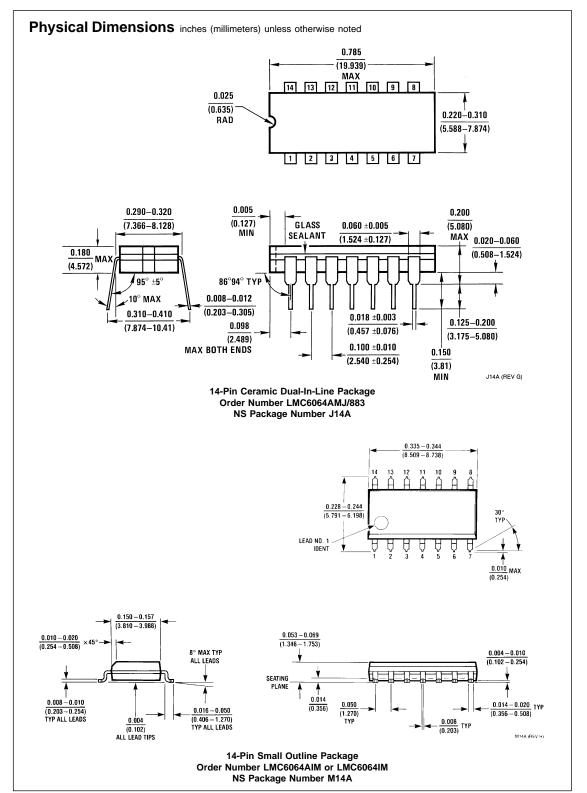
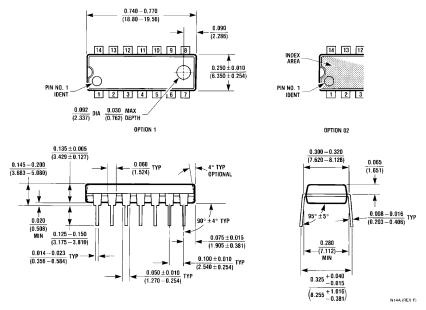


FIGURE 9. 1 Hz Square Wave Oscillator



Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



14-Pin Molded Dual-In-Line Package Order Number LMC6064AMN, LMC6064AIN or LMC6064IN NS Package Number N14A

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